Tool ID: 217
Tool Location: 114

Equipment Information Sheet

YES Asher

Manager: Aaron Windsor 607-254-4831
Backup: Tom Pennell 607-254-4309

Calls to staff phones will be automatically forwarded to their cell phones during accessible hours. At other times leave a message or send them an email.

SAFETY

- CAUTION! Do Not Touch THE WAFER STAGE when it is HOT!!

USAGE RESTRICTIONS

SCHEDULING/SIGN-UP RESTRICTIONS

Minimum Tool Time: 3 minutes

- Scheduling is restricted to a maximum of 2 hour blocks seperated by no less than 1 hour.

MATERIALS COMPATIBILITY CATEGORY

Tool Category 4: Glass and Metal Categories

Allowed	Not Allowed
Tool category 1/1E, 2, and 3 materials	
Silicon Based Substrates and Films	No CNF Class A metals
III/V compound Semiconductors	**No Exposed CNF Group B metals- *metals can be buried/covered with staff approval***
Glass Substrates	Cannot be used as an etch stop
PECVD and ALD Films	
Buried Class B Metals with approval	
Organic/Bio Materials prepped w/o Salt Buffers	
Cured organics and baked Photoresist	No High Vapor pressure materials

High Vapor Pressure Metals and Compounds are materials that have a vapor pressure above 1e-6 Torr at 400 C.

Additional Material Restrictions and Exceptions

- For removal of thin (< 10 micron) organic films. Thicker films must be cleared through Machine Manager.
- Wafers or samples must be clean on back.

Last Updated: 02/19/2024